

SLOTOCOUP SF 80 电镀铜填孔

新时代适用高阶载板制程高均匀电镀填孔系统

New-generation high uniformity BMV filling technology for advance substrate application

SLOTOCOUP SF 80 是一款领先的电镀铜化学添加剂, 具备高均匀性且方正低圆弧率线路等两大特性, 专为高阶 PCB 制程而设计, 提前布局满足高阶载板产品需求

SLOTOCOUP SF 80 BMV filling technology provides exceptional copper plating distribution and low flat-ratio trace shape. This enhances performance to meet the requirements of advanced substrate manufacturing.

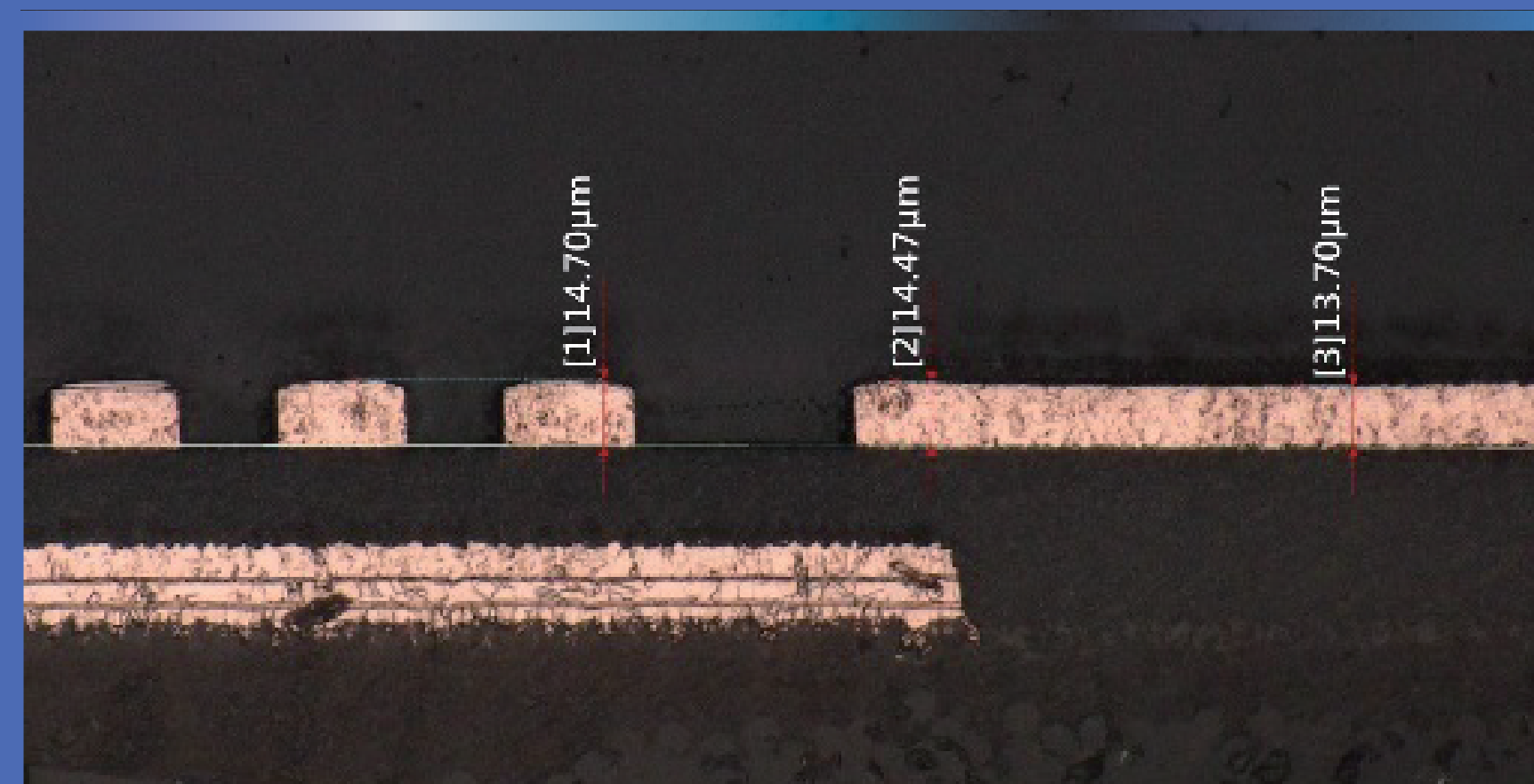
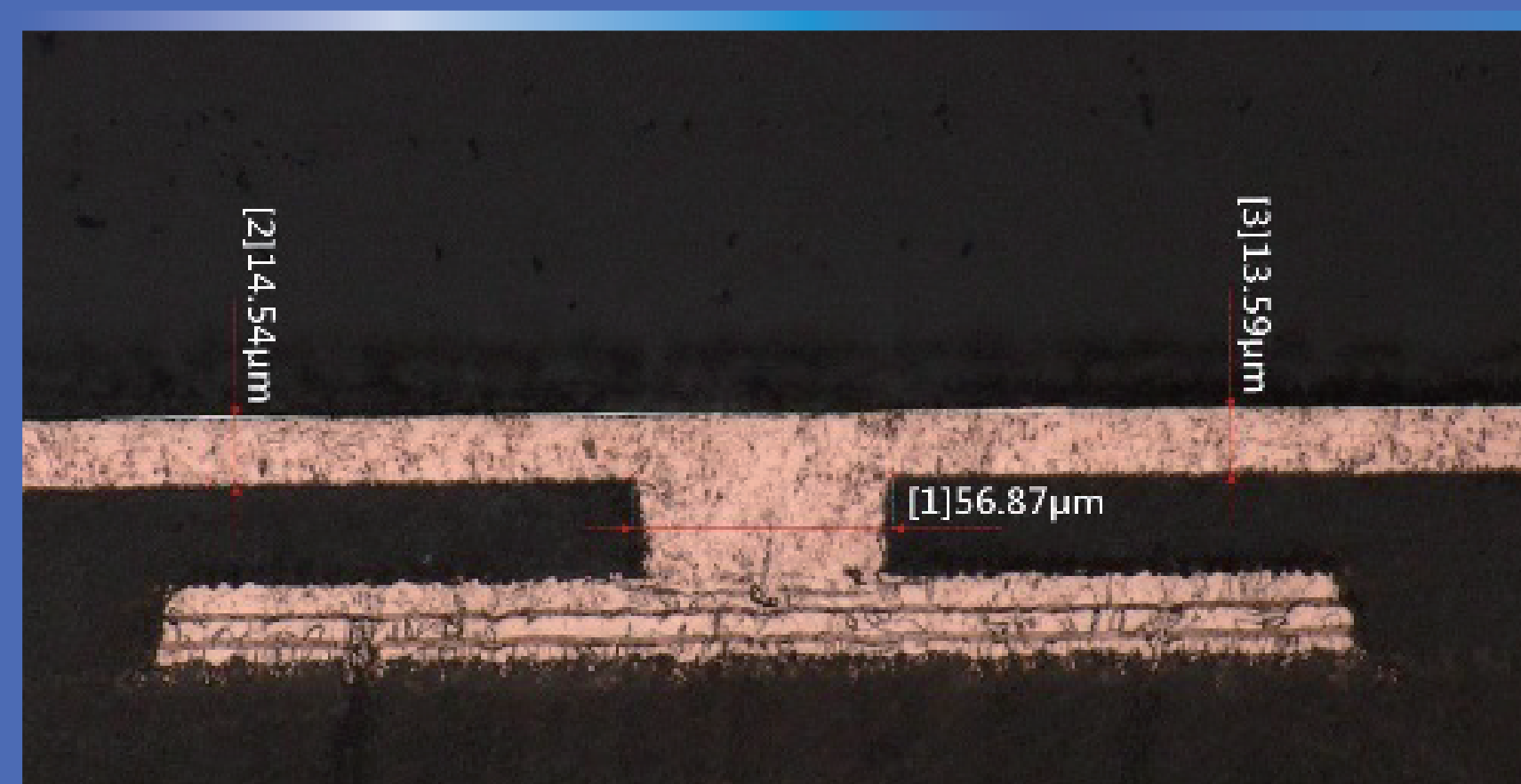
产品优势 Benefits

提升电镀铜厚均匀性

Outstanding plating copper distribution

有效缩小电镀铜厚差异

Effective to minimize the R value



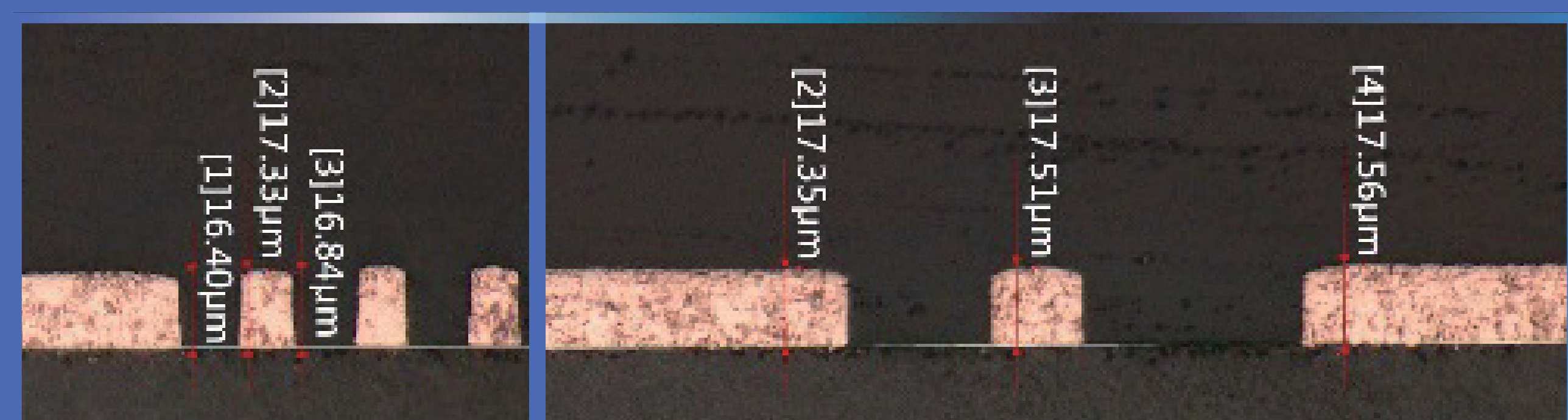
THK 14µm Dimple < 3µm R < 3µm

方正低圆弧率的线路

Low profile trace shape

SLOTOCOUP SF 80 线型表现

SLOTOCOUP SF 80 trace shape



线路平坦度 ~ 10%
Flat ratio ~ 10%

常见电镀填孔线型表现

Ordernary BMV filling technology trace shape



线路平坦度 > 20%
Flat ratio > 20%

应用领域 Application

超大尺寸载板

Mega scale unit IC substrate

高频高速运算载板

Hyper computing IC substrate

CO₂ 足迹 CO₂ Footprint

SF 81 SF 82 SF 83

Carbon Footprint for
Minimal vs. Maximal
Chemistry Consumption

